





#### **FEATURES**

#### **APPLICATIONS**

CMOS Output Low RMS Jitter Performance 12 kHz to 20 MHz (1 ps max, 156.25 MHz) RoHS 6/6 Compliant Base station controllers Ethernet Test and Measurement

### **Ordering Information:**

Product Family (Supply Voltage Option)	Temperature Range		Stability		Enable/Disable		Logic Type		Package/Lead Configuration		Frequency MHz
	Code	Value	Code	Value	Code	Value	Code	Value	Code	Value	
M2700 (3.3V) M2701 (2.5V)	6 2	-20 °C to +70 °C -40 °C to +85 °C	3 4 6 8	±100 ppm ±50 ppm ±25 ppm ±20 ppm	Т	Enable High (pad 1)	С	CMOS 45/55	N	Leadless	XXX.XXXXX
Example: M270024TCN 100.000000 MHz  M2700											

### **Electrical Specifications:**

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions				
Frequency of Operation	Fo	10		250	MHz					
		Free	quency Sta	ability						
Frequency Stability	ΔF/F		See ordering	g information						
Aging		-3		+3	ppm	1 <sup>st</sup> year				
			RF Outpu	t						
Output Type		CN	/IOS Compa	tible						
Output Load		15	pF CMOS I	oad						
Symmetry (duty cycle)		45		55	%	Ref. to 50% Vdd				
Logic Level "0"	$V_{OL}$			10% Vdd	V					
Logic Level "1"	$V_{OH}$	90% Vdd			V					
Rise/Fall Time	$T_R/T_F$			5	ns	10% Vdd to 90% Vdd				
Start-up Time	T <sub>SU</sub>			10	ms	$T_{ambient} = +25^{\circ}C$				
Enable Logic (Pad 1)		70% V <sub>CC</sub> or N/C			V	Output Enabled				
Disable Logic (Pad 1)				30% V <sub>CC</sub>	V	Output Disabled to high-Z				
	Supply Voltage & Power Consumption									
Operating Voltage	V <sub>cc</sub>	3.135	3.300	3.465	V V	(M2700)				
	00	2.375	2.500	2.625	V	(M2701)				
Supply Current	I <sub>cc</sub>			60	mA					

Revision A 08/01/16



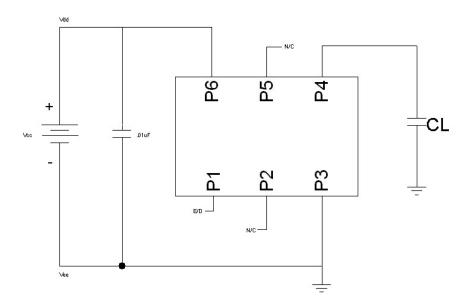




#### **Environmental & Packaging Requirements:**

Storage Temperature	-55°C to 125°C
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms)
Vibration	Per MIL-STD-202, Method 204D, Condition C (10 g's, 55 – 2000 Hz)
Aging	+85°C ±3°C, 720H (No BIAS)
Humidity	+40°C ±2°CX90~95%, 96H (NO BIAS)
Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B (-55 °C to +125 °C, 10 cycles)
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 <sup>-8</sup> atm cc/s of Helium)
Moisture Sensitivity Level	MSL1
Solderability	Per EIAJ-STD-002, Method 208
Max. Soldering Conditions	See solder profile, Figure 1
Pad Termination	Gold, 1 µm maximum thickness
Package Type	6-pad 5.0 X 7.0 mm leadless ceramic. RoHS compliant.

### **Typical CMOS Test Circuit & Load Circuit Diagrams:**









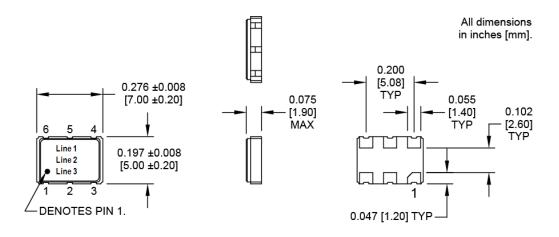
#### Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	No Connection
3	Ground
4	Output
5	No Connection
6	+V <sub>cc</sub>

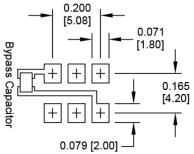
Part Marking								
Line 1	Line 1 [part designation]							
Line 2	FFFMFFFF							
Line 3	M yy ww vv							

	Legend							
M	M MtronPTI							
F	Frequency							
уу	Year							
ww	Work Week							
VV	Factory code							

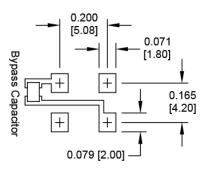
#### **Dimensions:**



#### SUGGESTED SOLDER PAD LAYOUT 6-PAD FOOTPRINT



## SUGGESTED SOLDER PAD LAYOUT 4-PAD FOOTPRINT

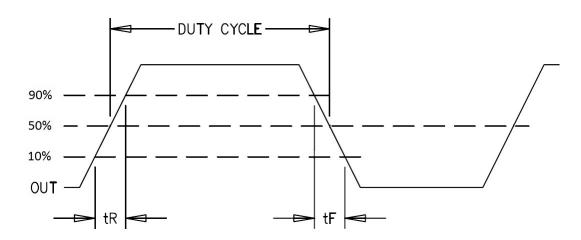








### **Output Waveform:**



### **Soldering Conditions:**

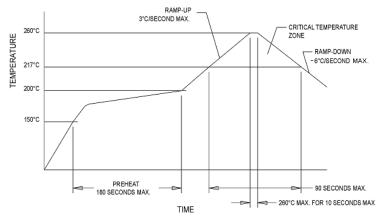


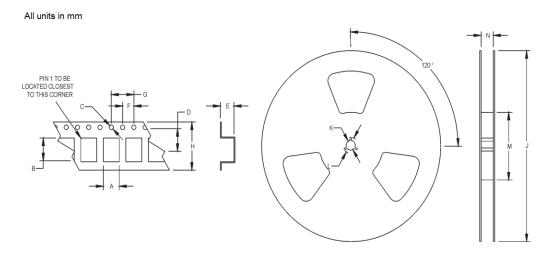
Figure 1







### **Tape and Reel Specifications:**



Tape and Reel Specifications											
Α	В	С	D	Е	F	G	Н	J	K	L	M
5.32	7.28	1.5	7.5	2.2	4	8	16	178	13.5	24.8	80